

TRISIL™ FOR TELECOM EQUIPMENT PROTECTION

FEATURES

- Bidirectional crowbar protection
- Voltage range from 62V to 270V
- Low capacitance from 12pF to 20pF @ 50V
- Low leakage current : $I_R = 2\mu A$ max
- Holding current: $I_H = 150$ mA min
- Repetitive peak pulse current :
 $I_{PP} = 50$ A (10/1000μs)

MAIN APPLICATIONS

Telecommunication equipment such as:

- Analog and digital line cards (xDSL, T1/E1, ISDN, ...)
- Terminals (phone, fax, modem, ...) and central office equipment

DESCRIPTION

These Trisil series have been designed to protect telecommunication equipment against lightning and transient induced by AC power lines. They are available in SMA, SMB and DO-15 packages.

BENEFITS

Trisils are not subject to ageing and provide a fail safe mode in short circuit for a better protection. They are used to help equipment to meet various standards such as UL1950, IEC950 / CSA C22.2, UL1459 and FCC part 68.

Trisils have UL94 V0 approved resin.

SMA and SMB packages are JEDEC registered (DO-214AC and DO-214AA).

Trisils are UL497B approved (file: E136224).

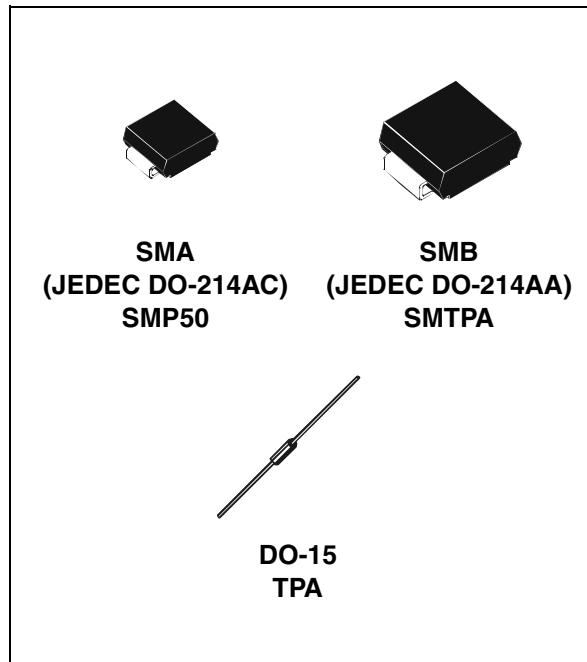
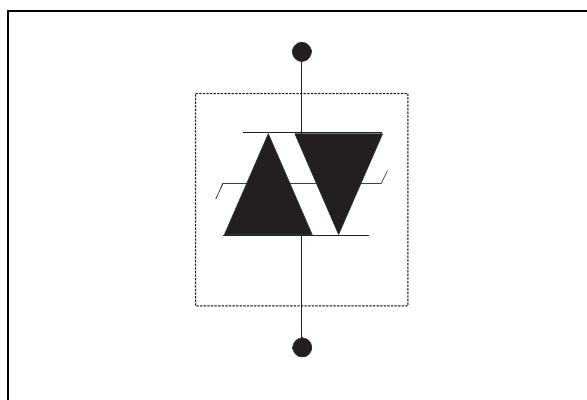


Table 1: Order Codes

Part Number	Marking
SMP50-xxx	
TPAxxx	See page 9
SMTPAxxx	

Figure 1: Schematic Diagram



SMP50 / SMTPA / TPA

Table 2: In compliances with the following standards

STANDARD	Peak Surge Voltage (V)	Waveform Voltage	Required peak current (A)	Current waveform	Minimum serial resistor to meet standard (Ω)
GR-1089 Core First level	2500 1000	2/10 μ s 10/1000 μ s	500 100	2/10 μ s 10/1000 μ s	20 10
GR-1089 Core Second level	5000	2/10 μ s	500	2/10 μ s	40
GR-1089 Core Intra-building	1500	2/10 μ s	100	2/10 μ s	0
ITU-T-K20/K21	6000 1500	10/700 μ s	150 37.5	5/310 μ s	53 0
ITU-T-K20 (IEC61000-4-2)	8000 15000	1/60 ns	ESD contact discharge ESD air discharge		0 0
VDE0433	4000 2000	10/700 μ s	100 50	5/310 μ s	21.5 0
VDE0878	4000 2000	1.2/50 μ s	100 50	1/20 μ s	0 0
IEC61000-4-5	4000 4000	10/700 μ s 1.2/50 μ s	100 100	5/310 μ s 8/20 μ s	21.5 0
FCC Part 68, lightning surge type A	1500 800	10/160 μ s 10/560 μ s	200 100	10/160 μ s 10/560 μ s	12.5 6.5
FCC Part 68, lightning surge type B	1000	9/720 μ s	25	5/320 μ s	0

Table 3: Absolute Ratings ($T_{amb} = 25^\circ C$)

Symbol	Parameter	Value	Unit
I_{PP}	Repetitive peak pulse current (see figure 2)	10/1000 μ s 8/20 μ s 10/560 μ s 5/310 μ s 10/160 μ s 1/20 μ s 2/10 μ s	50 100 55 65 75 100 100
I_{FS}	Fail-safe mode : maximum current (note 1)	8/20 μ s	2.5
I_{TSM}	Non repetitive surge peak on-state current (sinusoidal)	t = 0.2 s t = 1 s t = 2 s t = 15 mn	16 11.5 10 3.5
I^2t	I^2t value for fusing	t = 16.6 ms t = 20 ms	6.2 6.5
T_{stg} T_j	Storage temperature range Maximum junction temperature	-55 to 150 150	°C
T_L	Maximum lead temperature for soldering during 10 s.	260	°C

Note 1: in fail safe mode, the device acts as a short circuit

Table 4: Thermal Resistances

Symbol	Parameter	Value			Unit
		DO-15	SMA	SMB	
R _{th(j-a)}	Junction to ambient (with recommended footprint or with L _{lead} = 10mm for DO-15)	100	120	100	°C/W
R _{th(j-l)}	Junction to leads (L _{lead} = 10mm for DO-15)	60	30	20	°C/W

Table 5: Electrical Characteristics (T_{amb} = 25°C)

Symbol	Parameter
V _{RM}	Stand-off voltage
V _{BR}	Breakdown voltage
V _{BO}	Breakover voltage
I _{RM}	Leakage current
I _{PP}	Peak pulse current
I _{BO}	Breakover current
I _H	Holding current
V _R	Continuous reverse voltage
I _R	Leakage current at V _R
C	Capacitance

Types	I _{RM} @ V _{RM}		I _R @ V _R		Dynamic V _{BO}		Static V _{BO} @ I _{BO}		I _H	C typ.	C typ.
	max.		max.		note1	note 2	note 3	note 4	note 5	note 6	
	μA	V	μA	V	V	V	mA	mA	pF	pF	
SMP50-62 / TPA62 SMTPA62	2	56	5	62	85	82	800	150	20	40	
SMP50-68 / TPA68 SMTPA68		61		68	93	90			20	40	
SMP50-100 / TPA100 SMTPA100		90		100	135	133			16	35	
SMP50-120 / TPA120 SMTPA120		108		120	160	160			16	30	
SMP50-130 / TPA130 SMTPA130		117		130	173	173			14	30	
SMP50-180 / TPA180 SMTPA180		162		180	235	240			14	25	
SMP50-200 / TPA200 SMTPA200		180		200	262	267			12	25	
SMP50-220 / TPA220 SMTPA220		198		220	285	293			12	25	
SMP50-240 / TPA240 SMTPA240		216		240	300	320			12	25	
SMP50-270 / TPA270 SMTPA270		243		270	350	360			12	25	

Note 1: I_R measured at V_R guarantee V_{BR} min ≥ V_R

Note 2: see functional test circuit 1

Note 3: see test circuit 2

Note 4: see functional holding current test circuit 3

Note 5: V_R = 50V bias, VRMS=1V, F=1MHz

Note 6: V_R = 2V bias, VRMS=1V, F=1MHz

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Figure 2: Pulse waveform (10/1000μs)

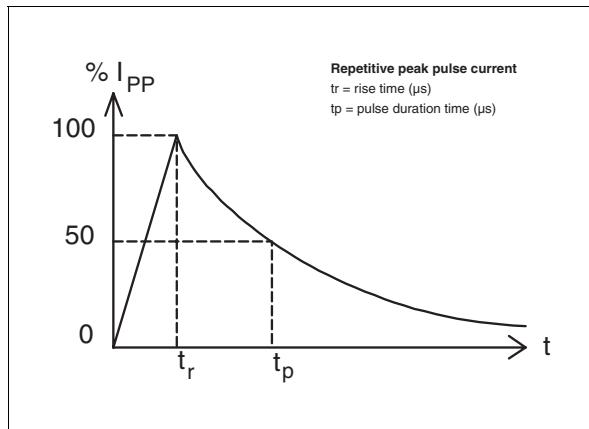


Figure 4: On-state voltage versus on-state current (typical values)

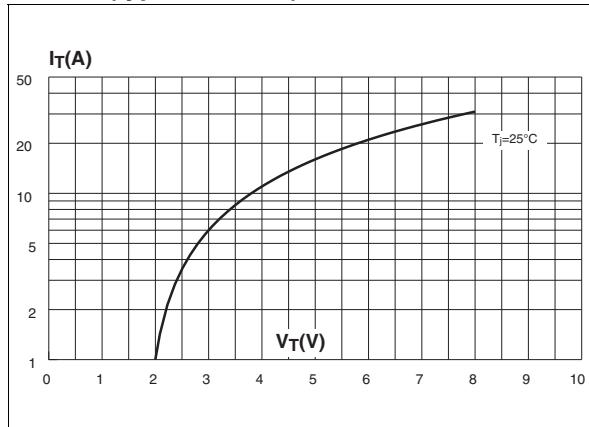


Figure 6: Relative variation of breakdown voltage versus junction temperature

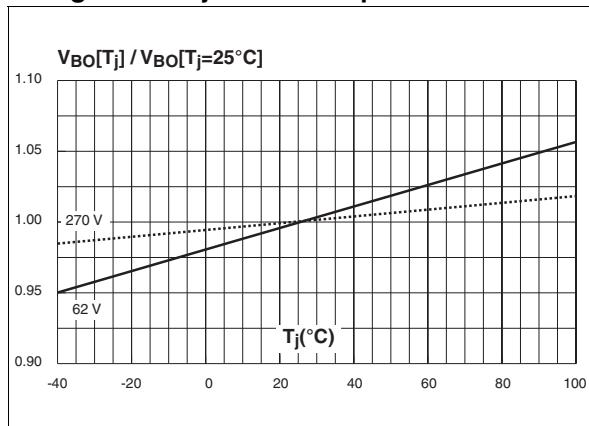


Figure 3: Non repetitive surge peak on-state current versus overload duration

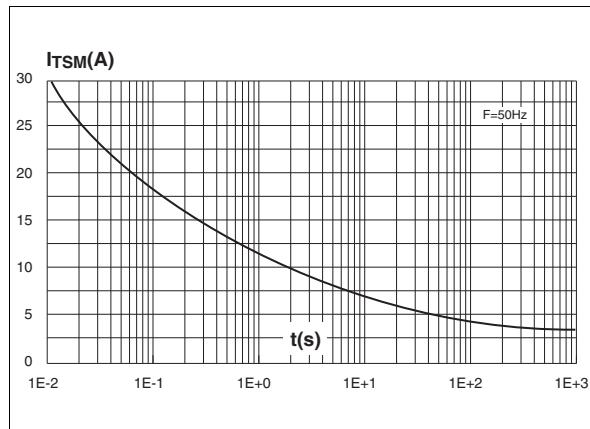


Figure 5: Relative variation of holding current versus junction temperature

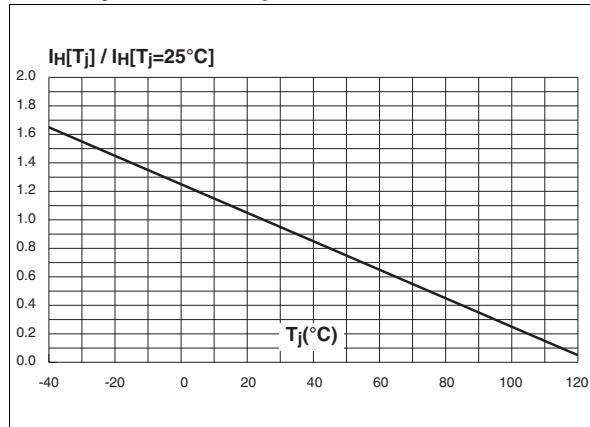


Figure 7: Relative variation of leakage current versus reverse voltage applied (typical values)

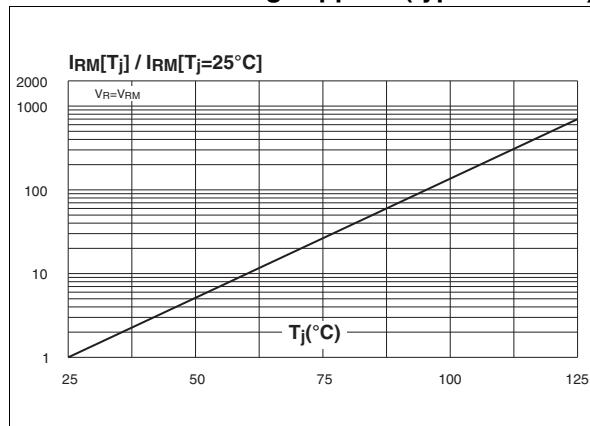


Figure 8: Variation of thermal impedance junction to ambient versus pulse duration (Printed circuit board FR4, SCu=35µm, recommended pad layout)

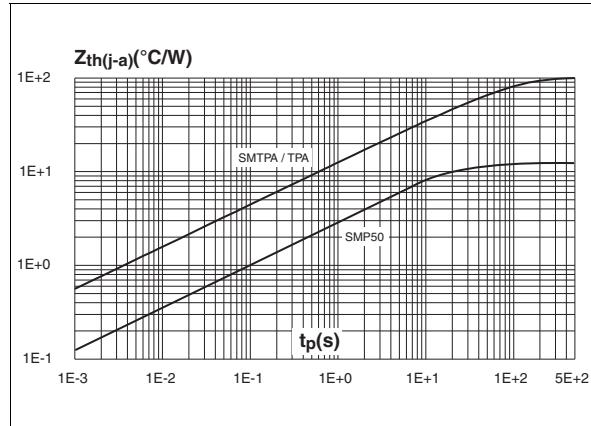


Figure 9: Relative variation of junction capacitance versus reverse voltage applied (typical values)

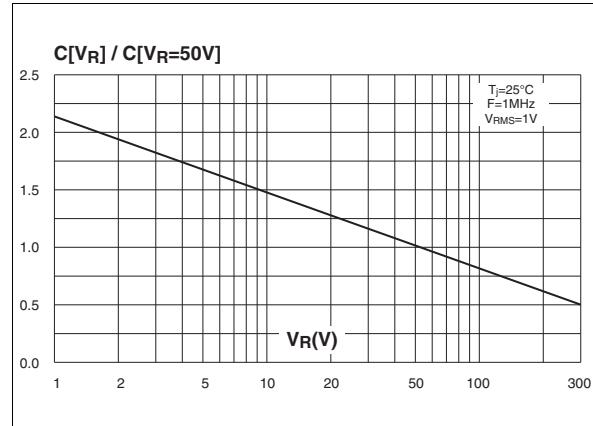
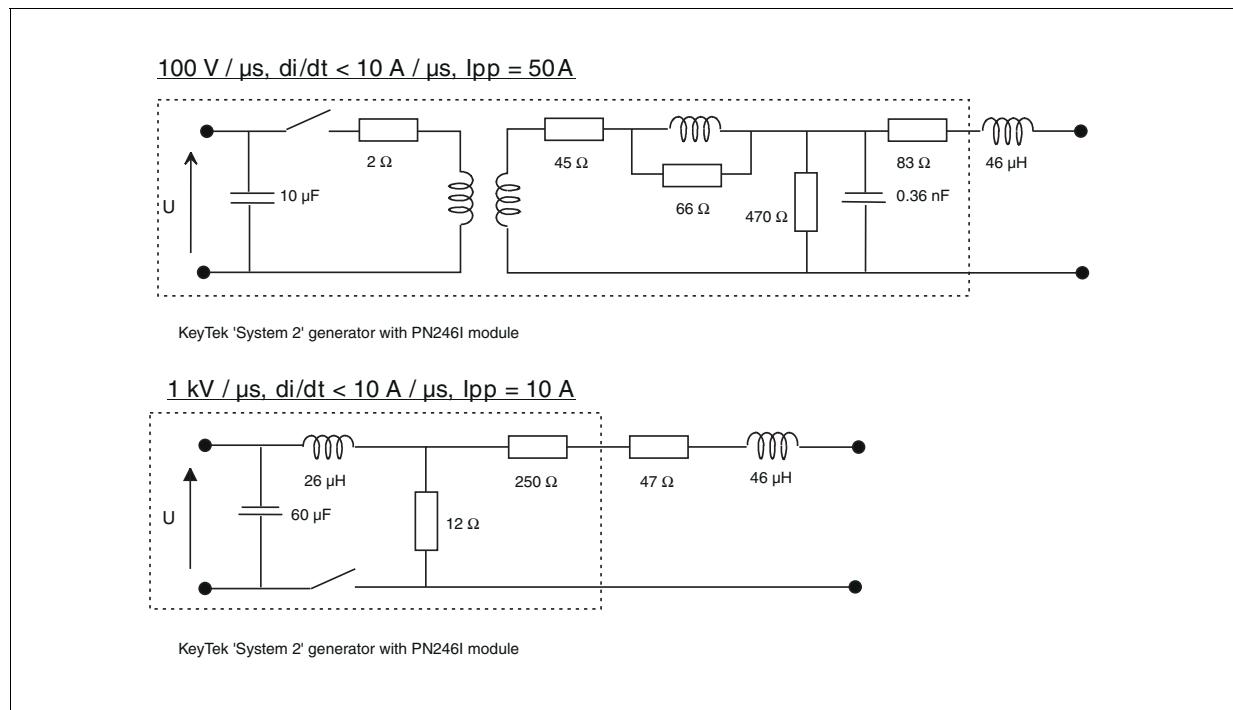


Figure 10: Test circuit 1 for Dynamic I_{BO} and V_{BO} parameters



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Figure 11: Test circuit 2 for I_{BO} and V_{BO} parameters

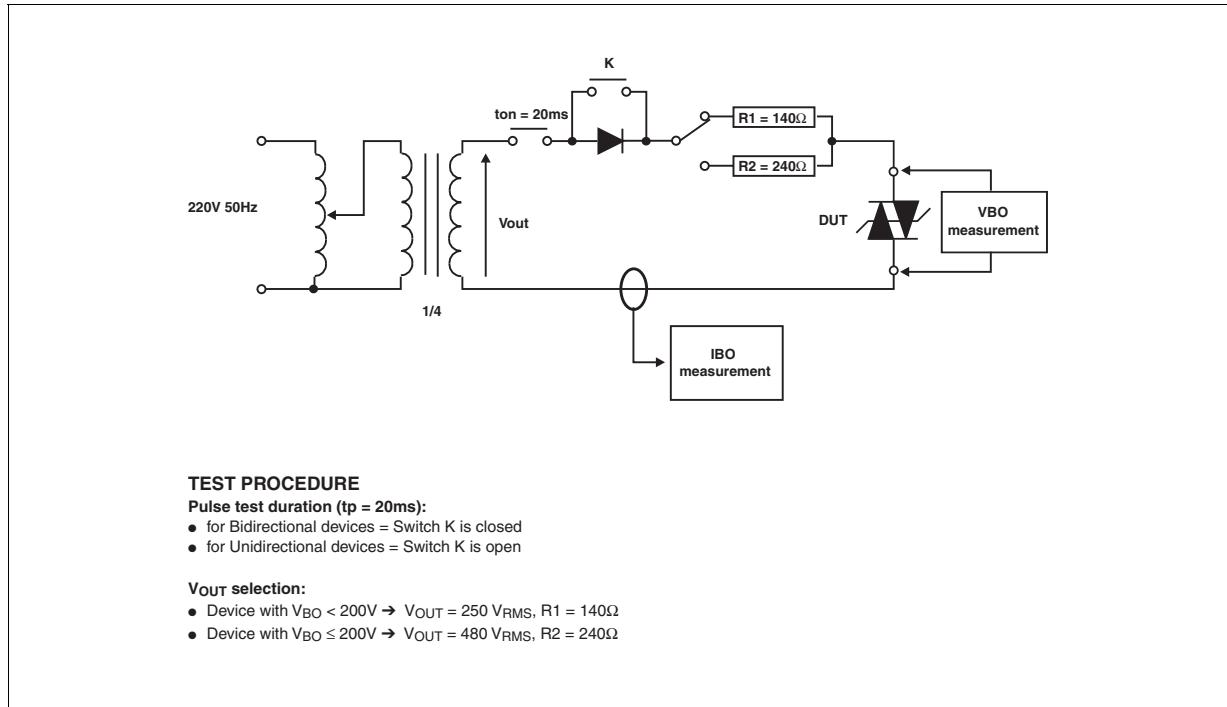


Figure 12: Test circuit 3 for dynamic I_H parameters

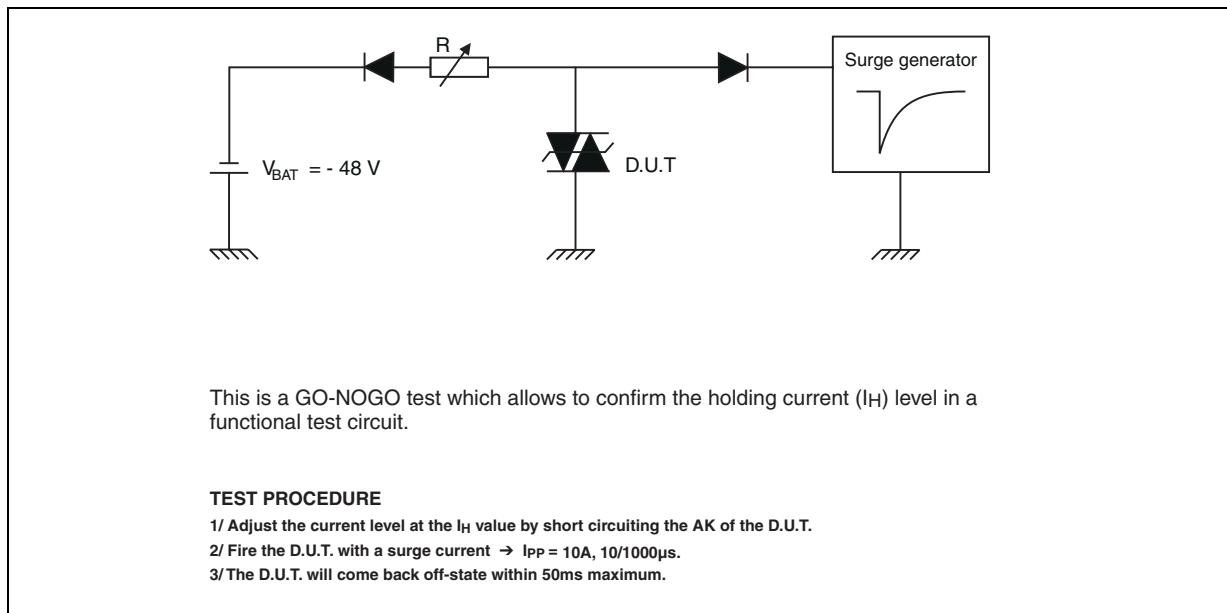


Figure 13: Ordering Information Scheme

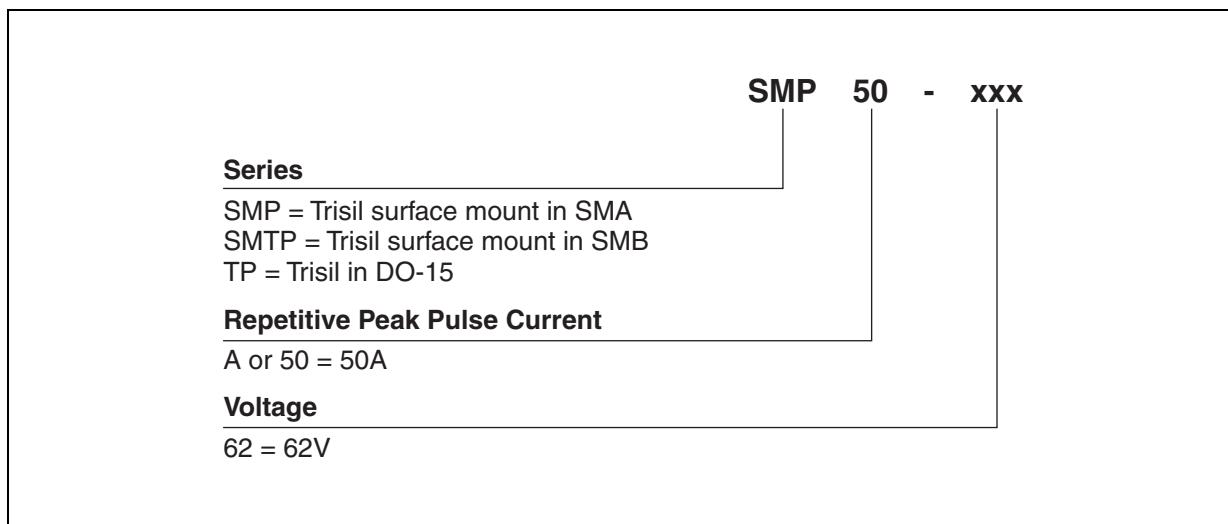


Figure 14: SMA Package Mechanical Data

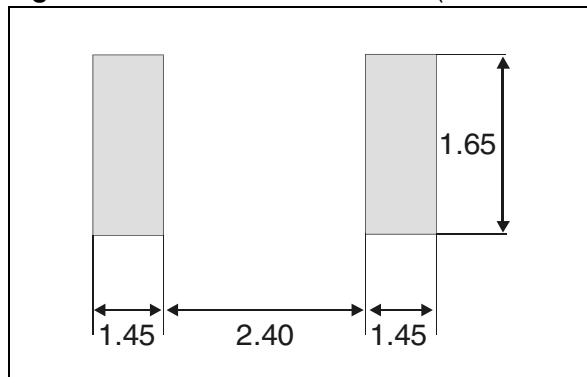
The diagram shows three views of the SMA package mechanical data:

- Top view: Shows width E_1 and height D .
- Side view: Shows width E , height b , and thickness c .
- Bottom view: Shows height A_1 , width A_2 , and width b .

REF.

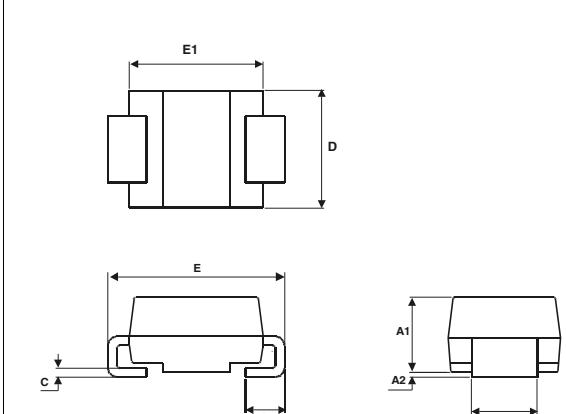
REF.	DIMENSIONS			
	Millimeters		Inches	
	Min.	Max.	Min.	Max.
A1	1.90	2.03	0.075	0.080
A2	0.05	0.20	0.002	0.008
b	1.25	1.65	0.049	0.065
c	0.15	0.41	0.006	0.016
E	4.80	5.60	0.189	0.220
E_1	3.95	4.60	0.156	0.181
D	2.25	2.95	0.089	0.116
L	0.75	1.60	0.030	0.063

Figure 15: Foot Print Dimensions (in millimeters)



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Figure 16: SMB Package Mechanical Data



REF.	DIMENSIONS			
	Millimeters		Inches	
	Min.	Max.	Min.	Max.
A1	1.90	2.45	0.075	0.096
A2	0.05	0.20	0.002	0.008
b	1.95	2.20	0.077	0.087
c	0.15	0.41	0.006	0.016
E	5.10	5.60	0.201	0.220
E1	4.05	4.60	0.159	0.181
D	3.30	3.95	0.130	0.156
L	0.75	1.60	0.030	0.063

Figure 17: Foot Print Dimensions (in millimeters)

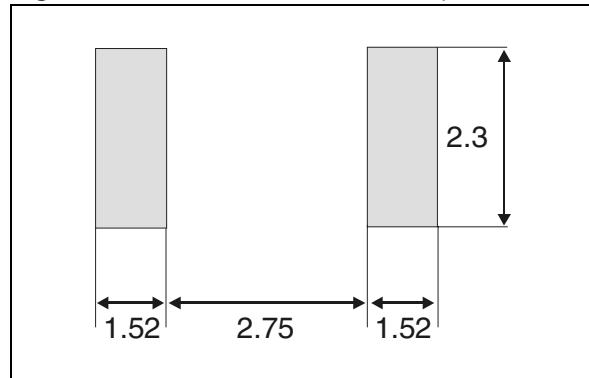
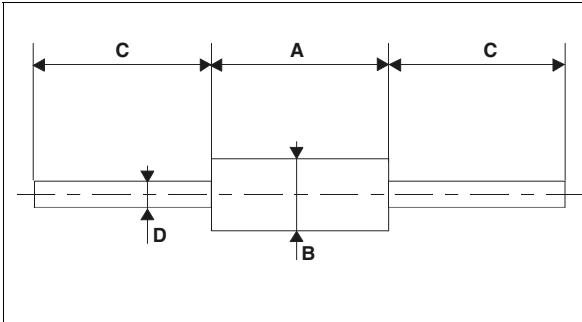


Figure 18: DO-15 Package Mechanical data



REF.	DIMENSIONS			
	Millimeters		Inches	
	Min.	Max.	Min.	Max.
A	6.05	6.75	0.238	0.266
B	2.95	3.53	0.116	0.139
C	26	31	1.024	1.220
D	0.71	0.88	0.028	0.035

Table 6: Ordering Information

Part Number	Marking	Package	Weight	Base qty	Delivery mode		
SMP50-62	V06	SMA	0.068 g	5000	Tape & reel		
SMP50-68	V07						
SMP50-100	V10						
SMP50-120	V12						
SMP50-130	V13						
SMP50-180	V18						
SMP50-200	V20						
SMP50-220	V22						
SMP50-240	V24						
SMP50-270	V27						
SMTPA62	U01	SMB	0.11 g	2500	Tape & reel		
SMTPA68	U05						
SMTPA100	U13						
SMTPA120	U17						
SMTPA130	U19						
SMTPA180	U25						
SMTPA200	U27						
SMTPA220	U31						
SMTPA240	U35						
SMTPA270	U39						
TPA62	TPA62	DO-15	0.40 g	1000	Ammopack		
TPA62RL				6000	Tape & reel		
TPA68	TPA68			1000	Ammopack		
TPA68RL				6000	Tape & reel		
TPA100	TPA100			1000	Ammopack		
TPA100RL				6000	Tape & reel		
TPA120	TPA120			1000	Ammopack		
TPA130	TPA130			1000	Ammopack		
TPA130RL				6000	Tape & reel		
TPA180	TPA180			1000	Ammopack		
TPA180RL				6000	Tape & reel		
TPA200	TPA200			1000	Ammopack		
TPA200RL				6000	Tape & reel		
TPA220	TPA220			1000	Ammopack		
TPA220RL				6000	Tape & reel		
TPA240	TPA240			1000	Ammopack		
TPA240RL				6000	Tape & reel		
TPA270	TPA270			1000	Ammopack		
TPA270RL				6000	Tape & reel		

Table 7: Revision History

Date	Revision	Description of Changes
16-Nov-2004	1	SMP50, SMTPA and TPA datasheets merge.

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